

2017-2022 Asia and Regional High Density Interconnect (HDI) PCBs Industry Production, Sales and Consumption Status and Prospects Professional Market Research Report

<https://marketpublishers.com/r/230EE0BD14FEN.html>

Date: August 2017

Pages: 195

Price: US\$ 3,500.00 (Single User License)

ID: 230EE0BD14FEN

Abstracts

This report focus on Asia and Regional market, providing information on major players like manufacturers, suppliers, distributors, traders, customers, investors and etc., major types, major applications from global and major regions such as Europe, North America, China, Japan, Southeast Asia and etc. Data type include capacity, production, market share, price, revenue, cost, gross, gross margin, growth rate, consumption, import, export and etc. Industry chain, manufacturing process, cost structure, marketing channel are also analyzed in this report.

This report provides valuable information for companies like manufacturers, suppliers, distributors, traders, customers, investors and individuals who have interests in this industry.

Major companies are as follows:

IBIDEN Group

NCAB Group

Bittele Electronics

TTM Technologies

Unimicron

ATandS

SEMCO

Young Poong Group

ZDT

Unitech Printed Circuit Board

Major classifications are as follows:

4-6 Layers HDI PCBs

8-10 Layer HDI PCBs

10+ Layer HDI PCBs

Major applications are as follows:

Automotive (Engine Control Units; GPS; Dashboard Electronics)

Computers (Laptops; Tablets; Wearable Electronics; Internet of Things - IoT)

Communication (Mobile phones; Modules; Routers; Switches)

Major regions are as follows:

China

Japan

Korea

India

Indonesia

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